

## PATENT ASSIGNMENT

Electronic Version v08

Stylesheet Version v02

SUBMISSION TYPE:

NEW ASSIGNMENT

NATURE OF CONVEYANCE:

ASSIGNMENT OF ASSIGNOR'S INTEREST

## CONVEYING PARTY DATA

Name	Execution Date
Mihoko Yamamoto	2006-07-28
Kumiko Sera	2006-08-01
Hiroyuki Tominaga	2006-07-28
Tetsuhisa Araki	2006-07-28

## RECEIVING PARTY DATA

Name	Street Address	Internal Address	City	State/Country	Postal Code
Sony Corporation	7-35, Kitashinagawa 6-chome	Shinagawa-ku	Tokyo	JP	141-0001

## PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number	11434477

## CORRESPONDENCE DATA

FAX NUMBER: (908) 654-0415

*Correspondence will be sent via US Mail when the fax attempt is unsuccessful.*

When the customer number has been provided, the Office of Public Records will obtain the correspondence data from the official record on file at the USPTO.

CUSTOMER NUMBER: 000530

NAME OF PERSON SIGNING:

Dennis M. Smid

DATE SIGNED:

2006-08-08

Total Attachments: 2

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PATENT

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REEL: 018072 FRAME: 0576

## ASSIGNMENT

Docket Number : SONYJP 3,0-584  
Sony Ref. No.:S06P0572US00

WHEREAS, I, as a below named inventor, residing at the address stated next to my name, am a sole inventor (if only one name is listed below) or a joint inventor (if plural names are listed below) of certain new and useful improvements in:

### IMAGING SYSTEM AND SYSTEM CONTROL METHOD

for which application for Letters Patent of the United States of America was executed by me on the date indicated next to my name and address;

AND WHEREAS, Sony Corporation, a Japanese corporation with offices at 7-35, Kitashinagawa 6-chome, Shinagawa-ku, Tokyo, Japan (hereinafter referenced as ASSIGNEE) is desirous of acquiring all interest in, to and under said invention, said application disclosing the invention and in, to and under any Letters Patent or similar legal protection which may be granted therefor in the United States and in any and all foreign countries;

NOW THEREFORE, in consideration of the sum of One Dollar (\$1.00), and other good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, I, as a sole or joint inventor as indicated below, by these presents do hereby assign, sell and transfer unto the said ASSIGNEE, its successors, assigns, and legal representatives, my entire right, title and interest in the said invention, said application, including any divisions and continuations thereof, and in and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted for said invention, and in and to any and all priority rights and/or convention rights under the International Convention for the Protection of Industrial Property, Inter-American Convention Relating to Patents, Designs and Industrial Models, and any other international agreements to which the United States of America adheres, and to any other benefits accruing or to accrue to me with respect to the filing of applications for patents or securing of patents in the United States and countries foreign thereto, and I hereby authorize and request the Commissioner of Patents to issue the said United States Letters Patent to said ASSIGNEE, as the assignee of the whole right, title and interest thereto;

And I further agree to execute all necessary or desirable and lawful future documents, including assignments in favor of ASSIGNEE or its designee, as ASSIGNEE or its successors, assigns and legal representatives may from time-to-time present to me and without further remuneration, in order to perfect title in said invention, modifications, and improvements in said invention, applications and Letters Patent of the United States and countries foreign thereto;

And I further agree to properly execute and deliver and without further remuneration, such necessary or desirable and lawful papers for application for foreign patents, for filing subdivisions of said application for patent, and or, for obtaining any reissue or reissues of any Letters Patent which may be granted for my aforesaid invention, as the ASSIGNEE thereof shall hereafter require and prepare at its own expense;

And I further agree that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said application, said invention and said Letters Patent and legal equivalents in foreign countries as may be known and accessible to me and will testify as to the same in any interference or litigation related thereto;

And I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale.

And I hereby authorize and request my attorney(s) of record in this application to insert the application number and filing date of this application in the spaces that follow: Application Number: 11/434,477, Filing Date: May 15, 2006.

This assignment executed on the dates indicated below.

Docket Number : SONYJP 3.0-584  
Sony Ref No.: S06P0572US00

Mihoko YAMAMOTO

Name of First or Sole Inventor

Execution Date of U.S. Patent Application

Kanagawa, Japan

Residence of First or Sole Inventor

Mihoko Yamamoto

Signature of First or Sole Inventor

July 28, 2006

Date of this Assignment

Kumiko SERA

Name of Second Joint Inventor

Execution Date of U.S. Patent Application

Tokyo, Japan

Residence of Second Joint Inventor

Kumiko Sera

Signature of Second Joint Inventor

August 1, 2006

Date of this Assignment

Hiroyuki TOMINAGA

Name of Third Joint Inventor

Execution Date of U.S. Patent Application

Kanagawa, Japan

Residence of Third Joint Inventor

Hiroyuki Tominaga

Signature of Third Joint Inventor

July 28th, 2006

Date of this Assignment

Tetsuhisa ARAKI

Name of Fourth Joint Inventor

Execution Date of U.S. Patent Application

Saitama, Japan

Residence of Fourth Joint Inventor

Tetsuhisa Araki

Signature of Fourth Joint Inventor

July 28, 2006

Date of this Assignment

Name of Fifth Joint Inventor

Execution Date of U.S. Patent Application

Residence of Fifth Joint Inventor

Signature of Fifth Joint Inventor

Date of this Assignment